

PCN No.: O000-PCN-PA201403-03

Product / Process Change Notice

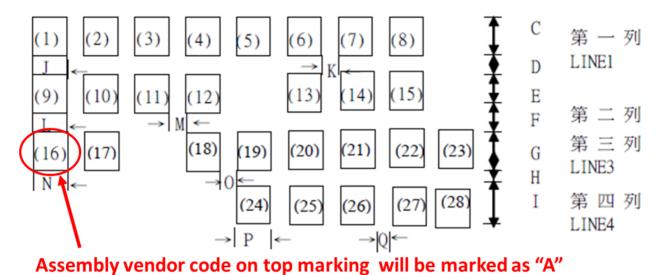
Date: 2014-03-25.

Change Title: Add ASE-CL as new assembly site for QFN 32L package products. Change Classification: ☑ Major ☐ Minor Change item: □ Design □ Raw Material □ Wafer FAB ☑ Package Assembly □ Testing □ Others: _____. Affected Product(s): The affected products are NAU8401YG, NAU8501YG and NAU8820YG. Description of Change(s): Add new assembly site for NAU8401YG, NAU8501YG and NAU8820YG products at ASECL (ASE Group ChungLi site, Taiwan). ASECL is a qualified vendor for Nuvoton in assembly, also ASECL had been passed several audits by international semiconductor corporations with automotive certification, please refer to appendix A for the details. New Supplier ASE Group ChungLi site, Taiwan (hereinafter "ASECL"), (550, Chung-Hwa Road Section 1, Chung-Li, 320, Taiwan, R.O.C.) Reason for Change(s): To increase manufacturing capacity and flexibility and to have multiple manufacturing routes for backup in case of disruption, Nuvoton is adding a new source of NAU8401YG, NAU8501YG and NAU8820YG products at ASECL. Impact of Change(s): (positive & negative) Form: No change on top effective marking except assembly vendor marking code. The assembly vendor marking code of ASECL shall be "A", as illustrated in fig.1. Fit: No change. Function: No change. Reliability: No concern (Passed Nuvoton package qualification.) Qualification Plan/Results: QFN packages were qualified as per Nuvoton's standard qualification procedures, please refer to appendix B & C for the qualification report." Implementation Plan: □ Date Code: ______ onward □ Lot No.: ______ onward □ Implemented date: _Jun. 23, 2014 (scheduled) HYLai / Q100 Originator: Approval:(QA Director) C.C. Chen/ Q000 Name: HYLai TEL: 886-3-5770066 (ext. 1226) FAX: 886-3-5792673. Contact for Questions & Address: No.4, Creation Rd. III Science-Based Industrial Park Hsinchu, Taiwan, Concerns R.O.C.. E-mail: hylai0@nuvoton.com.



☐ Approval ☐ ☐	Disapproval	☐ Conditional Approva	1:			<u>.</u>	
Date:	Dept. nan	ne:		Person in	n charge:		<u>.</u>
Follow-up and Tracing A. copies to	:						
FAB: □ Integration							
Test / Product: □ _]				·	
Design/ Marketing:]		•	
							<u></u> .
B. Changes:							
1. Document / Test pro	gram:						
Document No/ test	Document	name/ test program name	vers	ion	responsibor	Completed	Remark
program		. 0	before	after	·	date	
NA		NA	NA	NA	NA	NA	NA





Assembly vehicle code on top marking will be marked as 7.

Fig.1: The Assembly vendor code of ASECL on top marking will be marked as "A"

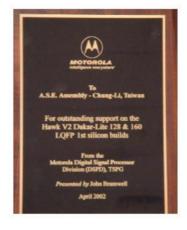


Appendix A: ASECL passed several audits by international semiconductor corporations.

Automotive Customer Award















© ASE Group. All rights reserved.





Automotive Customer Audit Result



The followings are summarized past Automotive Customer audit result on using Siemens VDA 6.3 checklist. All are above 90%.

Item No.	Customer	Audit Date	Audit Score
1	Sxx / Pxx	10 Jul 2007	91.1%
2	Fxx / Bxx	26 - 28 Nov 2007	92.0%
3	Fxx / Sxx	14 Jan 2008	92.0%
4	Sxx / Lxx	20 Jan 2009	94.0%
5	Cxx / Cxx	16 & 17 Feb 2009	91.0%
6	Fxx / Bxx	07 - 09 Jun 2010	90.3%
7	Sxx / Mxx	13 & 14 July 2011	97.0%
8	Sxx / Bxx	21 & 22 Nov 2011	95.0%
9	Sxx / Kxx	11 May 2012	97.0%
10	Fxx / Lxx	17 & 18 May 2012	99.5%
11	Fxx / Cxx	25 & 26 Oct 2012	94%
12	Fxx / Cxx	16 & 17 May 2013	94%
13	Axx / Cxx	13 & 14 June 2013	94%

Note: Some other Automotive Customers use their own Audit System which also showed Excellent result, such as Dxxx, Fxxx, Txxx, Kxxx, Cxxx, Txxx, Hxxx.



Appendix B: QFN packages qualification report for Cu wire.

nuvoton

PACKAGE QUALIFICATION REPORT

Company: ASE(Chung-Li)

Package: QFN Series

Package Material: GREEN

Wire Bonding Material: Cu wire

ASSISTANT MANAGER: 許心怡

RA MANAGER : 蔡明耀

Publication Release Date: May.2011



SUMMARY

The **QFN** series product was passed the qualification tests. A summary of the test result was as follows:

₽. Wire Pull Test : 5 units / 30 wires

₽. Ball Shear Test : 5 units /30 balls

₽. Pre-condition Test : 0/270 EA

₽. Pressure Cooker Test : 0/135 EA

₽. Temperature Cycle Test : 0/135 EA

□. Highly Temp. Storage Life Test : 0/135 EA



I. ENVIRONMENTAL TEST

A. Introduction

- 1. Wire Pull Test
- 2. Ball Shear Test
- 3. Pre-condition Test
- 4. Pressure Cooker Test (PCT)
- 5. Temperature Cycle Test (TCT)
- 6. High Temp. Storage Life Test(HTSL)

B. Test Results

- 1. Wire Pull Test
- 2. Ball Shear Test
- 3. Pre-condition Test
- 4. Pressure Cooker Test (PCT)
- 5. Temperature Cycle Test (TCT)
- 6. Highly Temp. Storage Life Test(HTSL)

I. ENVIRONMENTAL TESTS OF PROCEDURE

A. Introduction

- 1. Wire Pull Test
 - 1.1 SCOPE

Wire Pull Test is to measure the First bond and Second bond quality at the Assembly wire bonding process.

1.2 TEST CONDITION

5 units 30 wires $CPK \ge 1.66$



2. Ball Shear Test

2.1 SCOPE

Ball Shear Test is to measure the Copper ball quality on pad of chip.

2.2 Test condition:

5 units 30 balls CPK \geq 1.66

3. Pre-condition Test

3.1 SCOPE

Pre-condition Test is to measure the resistance of SMD (Surface Mount Devices) to the storage environment at the customer site and to thermal stress created by IR reflow or Vapor Phase Reflow.

3.2 TEST CONDITION

Step 1: TCT(-65°C/150°C, 5 cycles)

Step 2: Bake(125°C, 24 hours)

Step 3 : Soak(30°C/60%RH, 192 hours)

Step 4: IR reflow (260 °C), 3 Passes.

3.3 SAT COFIRMATION: To confirm delamination, cracking, popcorn .

Criteria: IPC/JEDEC J-STD-020D

3.4 IR REFLOW PROFILE (FOR IPC/JEDEC J-STD-020D)

Temp.	Criteria
Preheat 150 °C to 200 ° C	60~120 sec
Time maintained above: Above 217 ℃	60~150 sec
Peak temp	260 ℃ +0 ℃/-5 ℃



Time within 5 ℃ of actual Peak	
Temperature of peak	20~40 sec

4. Pressure Cooker Test (PCT)

4.1 SCOPE

PCT is to evaluate the device resistance to moisture penetration.

4.2 TEST CONDITION

Ta = 121°C, RH = 100%, Td = 168 Hrs. 2 ATM, (JESD22-A102-A)

5. Temperature Cycle Test (TCT)

5.1 SCOPE

TCT is to evaluate the resistance of device to environmental temperature change.

5.2 TEST CONDITION

-65°C / 15min, transfer time 1min, +150 °C/15min, 1000 cycles.

MIL-STD-883E, Method 1010, Condition "C".

6. Highly Temp. Storage Life Test (HTSL)

6.1 SCOPE

The purpose of this test is to determine the effect on solid state electronic devices of storage at elevated temperature without electrical stress applied.

6.2 Test condition:

Temperature: 150°C, Time: 1000hrs

B. Test Results

1. Wire Pull Test

Sample size : 5units / 30wires

Spec: ≥ 3 g

Max:11.697 g

Publication Release Date: Dec. 2010

- 5 -



Min: 9.603g

Avg.: 10.77 g

CPK: 4.988

Criteria : CPK ≥ 1.66

2. Ball Shear Test

Sample size : 5units / 30 balls

Spec: ≥ 15 g

Max: 17.787 g

Min: 15.238 g

Avg.: 16.651 g

CPK: 4.360

Criteria : CPK ≥ 1.66

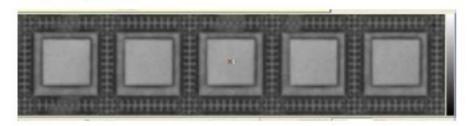
3.1 Pre-condition Test

Run	Lot No.	SAT before Precondition		SAT After Precondition		Electric result
		Topside	Backside	Topside	Backside	FT
#1	E037B006-ZX	0/135	0/135	0/135	0/135	0/135
#2	E037B006-ZY	0/135	0/135	0/135	0/135	0/135
#3	E037B006-ZZ	0/135	0/135	0/135	0/135	0/135



*Criteria: Acc/Rej = 0/1.

3.2 SAT confirmation: PASS



4. Pressure Cooker Test (PCT)

Run	Package	168 Hrs	Result	Remark
#1	E037B006-ZX	0/45	Pass	
#2	E037B006-ZY	0/45	Pass	
#3	E037B006-ZZ	0/45	Pass	

^{*}Criteria : Acc/Rej = 0/1.

5. Temperature Cycle Test (TCT)

Run	Package	1000 Cycles	Result	Remark
#1	E037B006-ZX	0/45	Pass	
#2	E037B006-ZY	0/45	Pass	3
#3	E037B006-ZZ	0/45	Pass	

^{*}Criteria: Acc/Rej = 0/1.

6. Highly Temp. Storage Life Test (HTSL)

Run	Package	1000 Hrs	Result	Remark
#1	E037B006-ZX	0/45	Pass	
#2	E037B006-ZY	0/45	Pass	



#3 E037B006-ZZ	0/45	Pass	
----------------	------	------	--

*Criteria : Acc/Rej = 0/1.

nuvoTon

Headquarter

No. 4, Creation Rd. Ⅲ, Hsinchu Science Park, 300 Taiwan, R.O.C. Tel: 886-3-5770066 http://www.nuvoton.com.tw/

Taipei Sales Office

9F, No. 480, Rueiguang Rd., Neihu Chiu, Taipei, 114, Taiwan, R.O.C. Tel: 886-2-26588066

Nuvoton Electronics Technology (H.K.) Limited

Unit 9-11, 22F, Millennium City 2, 378 Kwun Tong Road, Kowloon, Hong Kong Tel: 852-27513100

Nuvoton Electronics Technology (Shanghai) Limited

27F, 2299 Yan An Road (West), Shanghai, P.R. China Tel: 86-21-62365999

Nuvoton Electronics Technology (Shenzhen) Limited

Unit 1501, New World Center, 6009 Yitian Road, Futian, Shenzhen 518026, P.R.China Tel: 86-755-83515350

Nuvoton Technology Corp. America

2727 North First Street, San Jose, CA 95134, U.S.A. Tel:1-408-544-1718

Nuvoton Technology Israel Ltd.

8 Hasadnaot Street, Herzlia B, 46130, Israel Tel: 972-9-970-2000



Appendix B: QFN packages qualification report for Au wire.

nuvoTon

PACKAGE QUALIFICATION REPORT

Company: ASE group Chung-Li

PKG: QFN 36L(6x6x1.0max)

PKG MATERIAL: Green / Au wire

RA ENGINEER: IS Wang

RA SECTION MANAGER: (Fchang

RA MANAGER: Tany Chy



SUMMARY

The QFN 36L product was passed the qualification tests. A summary of the test result was as follows:

Fb. High Temp. Storage Life Test : 0/135 pcs

Fb. Pre-condition Test : 0/405 pcs

Fb. Pressure Cooker Test : 0/135 pcs

Fb. Thermal Shock Test : 0/135 pcs

Fb. Temperature Cycle Test : 0/135 pcs

Results of the life tests and environmental tests as well as the methods used on **QFN 36L** are described in details in the report.



---CONTENTS---

. LIFE TEST

A. Introduction

1. High Temp. Storage Life Test (HTSL)

B. Test Results

1. High Temp. Storage Life Test (HTSL)

. ENVIRONMENTAL TEST

A. Introduction

- 1. Pre-condition Test
- 2. Pressure Cooker Test (PCT)
- 3. Thermal Shock Test (TST)
- 4. Temperature Cycle Test (TCT)

B. Test Results

- 1. Pre-condition Test
- 2. Pressure Cooker Test (PCT)
- 3. Thermal Shock Test (TST)
- 4. Temperature Cycle Test (TCT)

1. LIFE TEST

A. Introduction

1. High Temperature Storage Life Test (HTSL)

1.1 SCOPE

HTSL test is to determine the stability of the device in high temperature environment.



NUVOTON

1.2 TEST CONDITION

Temp = 150 ℃ , Td = 1000 hrs.

(MIL-STD-883E, Method 1008, Condition "C")

B. Test Results

1. High Temperature Storage Life Test (HTSL)

1.1 SUMMARY TABLE

RUN	Lot No	1000 Hrs	Remark
#1	2621B010-ZX	0/45	
#2	2621B010-ZY	0/45	
#3	2621B010-ZZ	0/45	

II. ENVIRONMENTAL TESTS

A. Introduction

1. Pre-condition Test

1.1 SCOPE

Pre-condition Test is to measure the resistance of SMD (Surface Mount Devices) to the storage environment at the customer site and to thermal stress created by IR reflow or Vapor Phase Reflow.

1.2 TEST CONDITION

Step 1 : TCT(-65 °C/150 °C, 5 cycles)

Step 2 : Bake(125 °C, 24 hours)

Step 3 : Soak(30 ℃/60%RH, 192 hours)

Step 4: IR reflow (260 °C), 3 Passes.

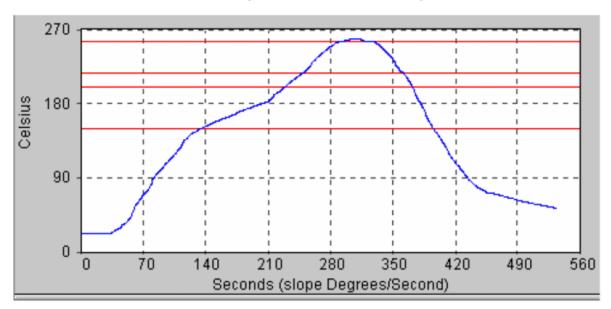
1.3 SAT COFIRMATION: To confirm delamination, cracking, popcorn .

Criteria: IPC/JEDEC J-STD-020C



NUVOTON

1.4 IR REFLOW PROFILE (FOR IPC/JEDEC J-STD-020C)



Temp.	Criteria	
Preheat 150 °C to 200 °C	60~180 sec	
Time maintained above: Above 217 ℃	60~150 sec	
Peak temp	260 °C +0 °C/-5 °C	
Time within 5 °C of actual Peak Temperature of peak	20~40 sec	

2. Pressure Cooker Test (PCT)

2.1 SCOPE

PCT is to evaluate the device resistance to moisture penetration.

2.2 TEST CONDITION

Ta = 121 °C, RH = 100%, Td = 168 Hrs. 2 ATM, (JESD22-A102-A)



3. Thermal shock Test (TST)

3.1 SCOPE

TST is conducted to determine the resistance of a part to sudden exposure to extreme changes in temperature and to the effect of alternate exposures to these extremes.

3.2 TEST CONDITION

T=-65°C / 150°C/, transition period = 5 minutes, 100 cycles.

MIL-STD-883; Method 1011

4. Temperature Cycle Test (TCT)

4.1 SCOPE

TCT is to evaluate the resistance of device to environmental temperature change.

4.2 TEST CONDITION

-65 °C / 15min, transfer time 1min, +150 °C/15min, 1000 cycles.

MIL-STD-883E, Method 1010, Condition "C".

B. Test Results

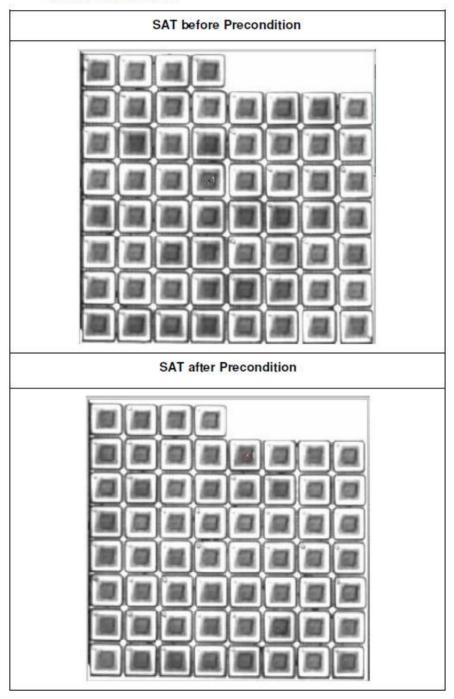
1.1 Pre-condition Test

Run	Lot No	SAT before	SAT After	Remark
		Precondition	Precondition	
		Topside	Topside	
#1	2621B010-ZX	0/135	0/135	
#2	2621B010-ZY	0/135	0/135	
#3	2621B010-ZZ	0/135	0/135	

*Criteria: Acc/Rej = 0/1.



1.2 SAT confirmation:





NUVOTON

2. Pressure Cooker Test (PCT)

Run	Lot No	168 Hrs	Remark
#1	2621B010-ZX	0/45	
#2	2621B010-ZY	0/45	
#3	2621B010-ZZ	0/45	

^{*}Criteria : Acc/Rej = 0/1.

3. Thermal Shock Test (TST)

Run	Lot No	100 Cycles	Remark
#1	2621B010-ZX	0/45	
#2	2621B010-ZY	0/45	
#3	2621B010-ZZ	0/45	

^{*}Criteria : Acc/Rej = 0/1.

4. Temperature Cycle Test (TCT)

Run	Lot No	1000 Cycles	Remark
#1	2621B010-ZX	0/45	
#2	2621B010-ZY	0/45	
#3	2621B010-ZZ	0/45	

^{*}Criteria: Acc/Rej = 0/1.



nuvoton

Headquarter

No. 4, Creation Rd. III, Heinchu Science Park, 300 Taiwan, R.O.C. Tel: 886-3-5770066 http://www.nuvoton.com.tw/

Taipei Sales Office 9F, No. 480, Rueiguang Rd., Neihu Chiu, Taipei, 114, Taiwan, R.O.C. Tel: 886-2-26588066

Nuvoton Electronics Technology (H.K.) Limited Unit 9-11, 22F, Millennium City 2, 378 Kwun Tong Road, Kowloon, Hong Kong Tel: 862-27513100

Nuvoton Electronics Technology (Shanghai) Limited

27F, 2299 Yan An Road (West), Shanghai, F.R. China Tel: 86-21-62365999

Nuvoton Electronics Technology (Shenzhen) Limited

Unit 1501, New World Center, 6009 Yitian Road, Fulian, Shenzhen 518026, P.R.China Tel. 86-755-83515350

Nuvoton Technology Corp. America 2727 North First Street, San Jose, CA 95134, Tel:1-408-544-1718

Nuvoton Technology Israel Ltd. 8 Hasadnaot Street, Herzlia B, 46130, Tel: 972 9 970 2000